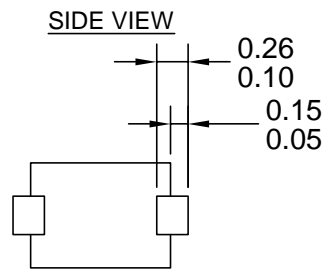
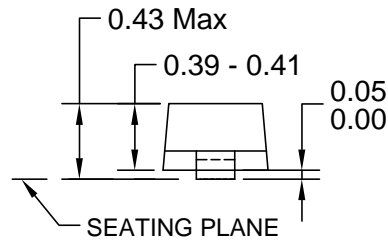
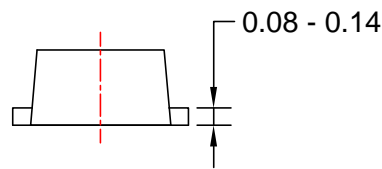
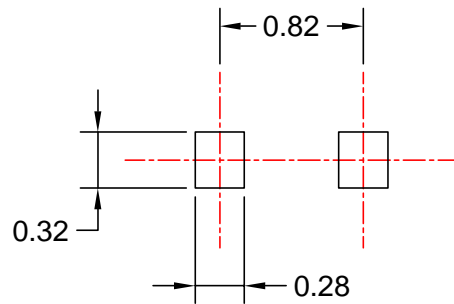
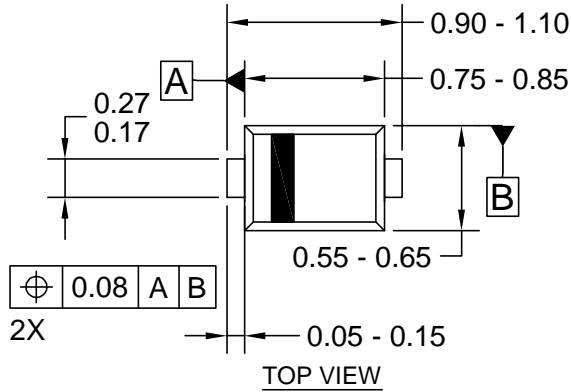


REVISIONS

NBR	DESCRIPTION	DATE	BY/SITE
1	RELEASE TO DOCUMENT CONTROL	Nov.15.2007	T.S KIM/BUCHEON
2	DIMENSIONS ADDED/ Leadform drawing change.	Jan.23.2008	T.S KIM/BUCHEON



NOTES:

- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) BODY DIMENSIONS ARE INCLUSIVE OF BURRS, AND MOLD FLASH.
- D) DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- E) LANDPATTERN BASED ON NOMINAL PACKAGE DIMENSIONS.
- F) DRAWING FILE NAME : SOD923F1REV2

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR®			
DRAWN	J. H MOON	Jan.23.2008				
DFTG. CHK.	H.ALLEN	Jan.23.2008				
ENGR. CHK.	T. S KIM	Jan.23.2008				
2LD, SOD923F, 0.4MM TALL, FLAT TERMINAL			SCALE	SIZE	DRAWING NUMBER	REV
INCH (MM)			1:1	N/A	MKT-SOD923F1	2
			FORMERLY: N/A	SHEET: 1 OF 1		